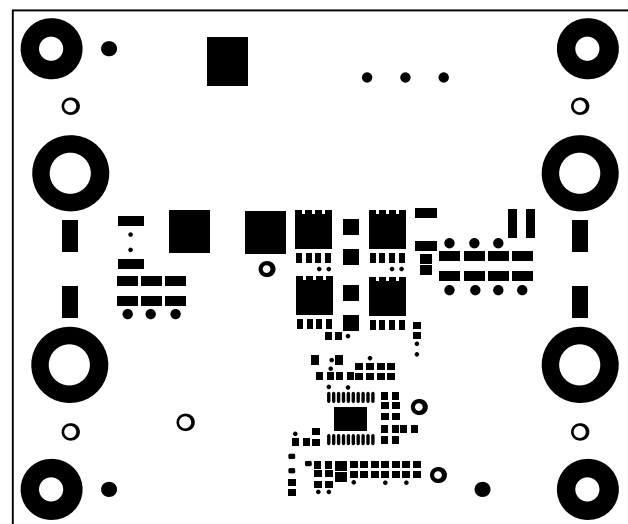
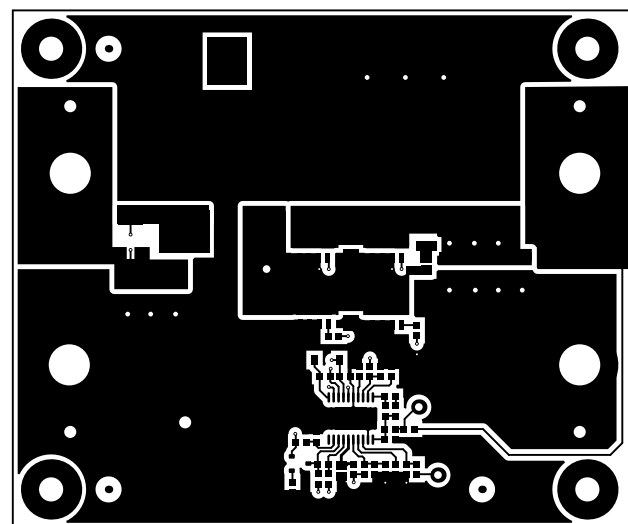


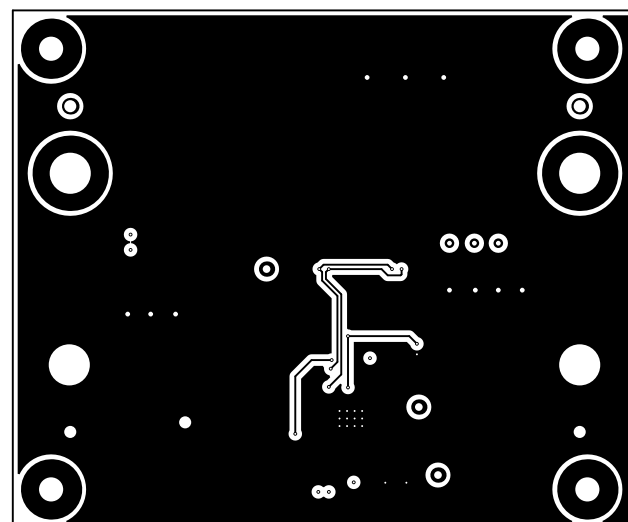
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP21274		
PLOT NAME = Top Overlay	GENERATED : 11/29/2017 2:54:32 PM	TEXAS INSTRUMENTS	



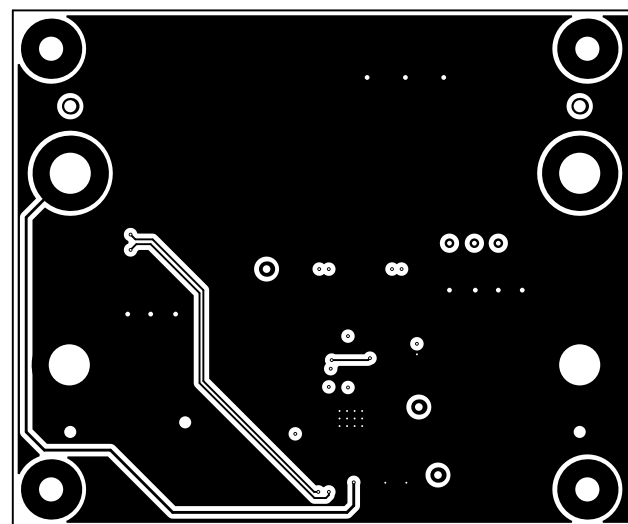
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP21274		
PLOT NAME = Top Solder Mask	GENERATED : 11/29/2017 2:54:33 PM	TEXAS INSTRUMENTS	



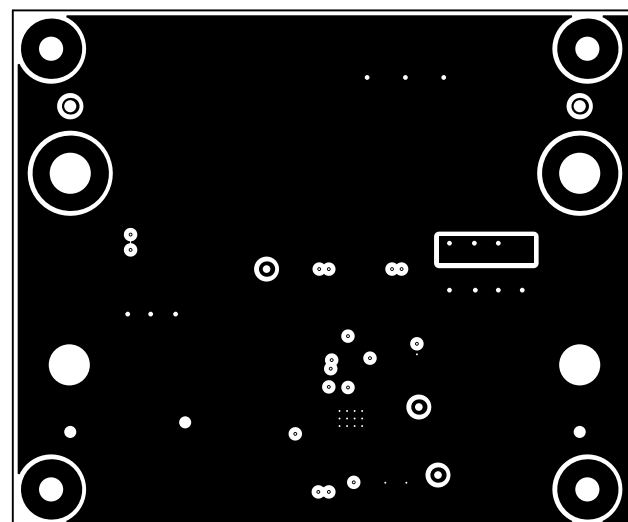
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP21274		
PLOT NAME = Top Layer	GENERATED : 11/29/2017 2:54:33 PM	TEXAS INSTRUMENTS	



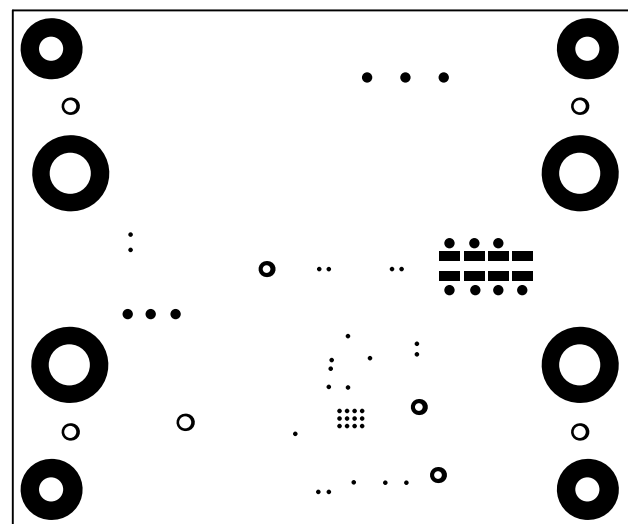
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP21274		
PLOT NAME = Signal Layer 1	GENERATED : 11/29/2017 2:54:34 PM	TEXAS INSTRUMENTS	



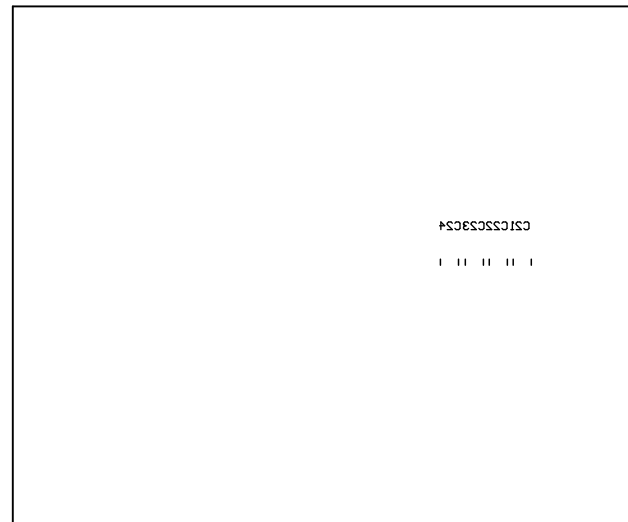
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP21274		
PLOT NAME = Signal Layer 2	GENERATED : 11/29/2017 2:54:35 PM	TEXAS INSTRUMENTS	



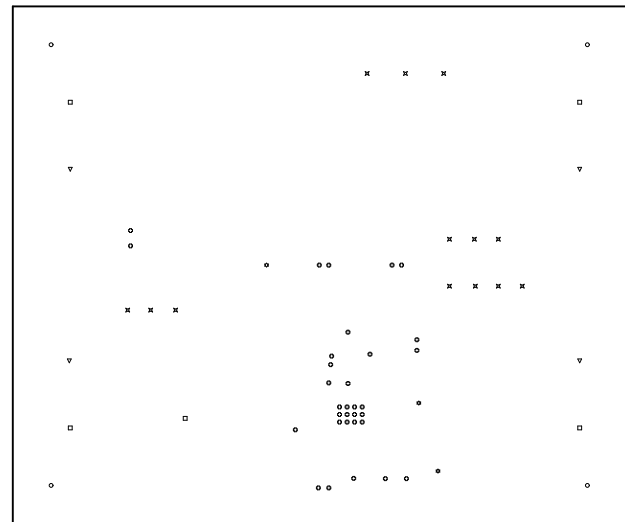
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP21274		
PLOT NAME = Bottom Layer	GENERATED : 11/29/2017 2:54:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP21274		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/29/2017 2:54:37 PM	TEXAS INSTRUMENTS	

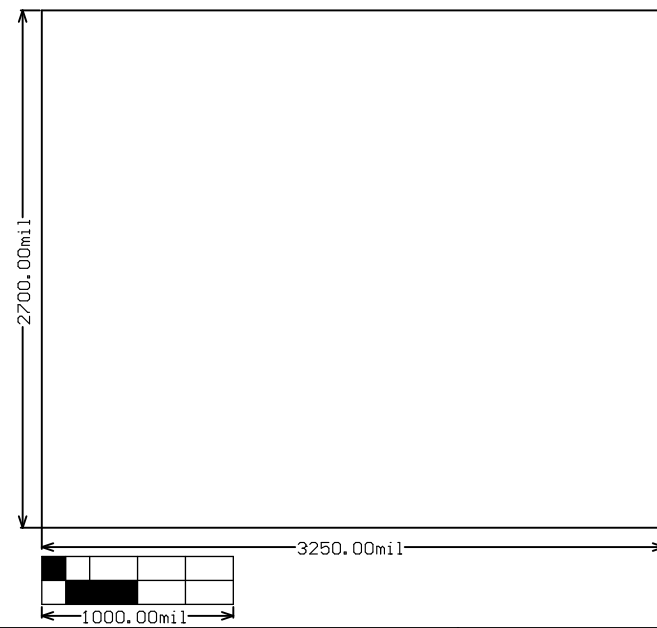


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP21274		
PLOT NAME = Bottom Overlay	GENERATED : 11/29/2017 2:54:38 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	32	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	13	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	5	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	61 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP21274		
PLOT NAME = Drill Drawing	GENERATED : 11/29/2017 2:54:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP21274		
PLOT NAME = Board Dimensions	GENERATED : 11/29/2017 2:54:40 PM	TEXAS INSTRUMENTS	

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